



Material Content Data Sheet



Sales Product Name		IPD50N06S4L-08		Issued		25. September 2017		
MA#		MA001068098						
Package		PG-TO252-3-11		Weight*		390.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.120	0.54	0.54	5424	5424
leadframe	inorganic material	phosphorus	7723-14-0	0.042	0.01		107	
	non noble metal	iron	7439-89-6	0.140	0.04		358	
	non noble metal	copper	7440-50-8	139.706	35.74	35.79	357419	357884
	non noble metal	aluminium	7429-90-5	1.516	0.39	0.39	3879	3879
wire	non noble metal	aluminium	7429-90-5	1.516	0.39	0.39	3879	3879
encapsulation	organic material	carbon black	1333-86-4	1.467	0.38		3754	
	plastics	epoxy resin	-	25.679	6.57		65696	
	inorganic material	silicondioxide	60676-86-0	119.589	30.60	37.55	305954	375404
leadfinish	non noble metal	tin	7440-31-5	3.740	0.96	0.96	9568	9568
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	232	233
solder	non noble metal	tin	7440-31-5	0.043	0.01		111	
	noble metal	silver	7440-22-4	0.054	0.01		139	
	non noble metal	lead	7439-92-1	2.074	0.53	0.55	5307	5557
heatspreader	inorganic material	phosphorus	7723-14-0	0.028	0.01		73	
	non noble metal	iron	7439-89-6	0.095	0.02		242	
	non noble metal	copper	7440-50-8	94.488	24.17	24.20	241736	242051
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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